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(12) **United States Design Patent**
Green et al.

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(54) SUBSTRATE PROCESSING SYSTEM CARRIER

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(**) Term: **15 Years**

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(51) **LOC (14) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/182**

(58) **Field of Classification Search**
USPC D13/123, 133, 146, 147, 158, 182, 184, D13/199, 149, 151, 154, 173
CPC H01R 13/42; H01R 13/436; H01R 13/52; H01R 13/53; H01R 13/64; H01R 13/648; H01R 13/73; H01R 24/20; B25J 15/08; B65G 47/90; H01L 21/672; H01L 21/673; H01L 21/67379; H01L 21/67383; H01L 21/677
See application file for complete search history.

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(74) *Attorney, Agent, or Firm* — Lowenstein Sandler LLP

(57) CLAIM

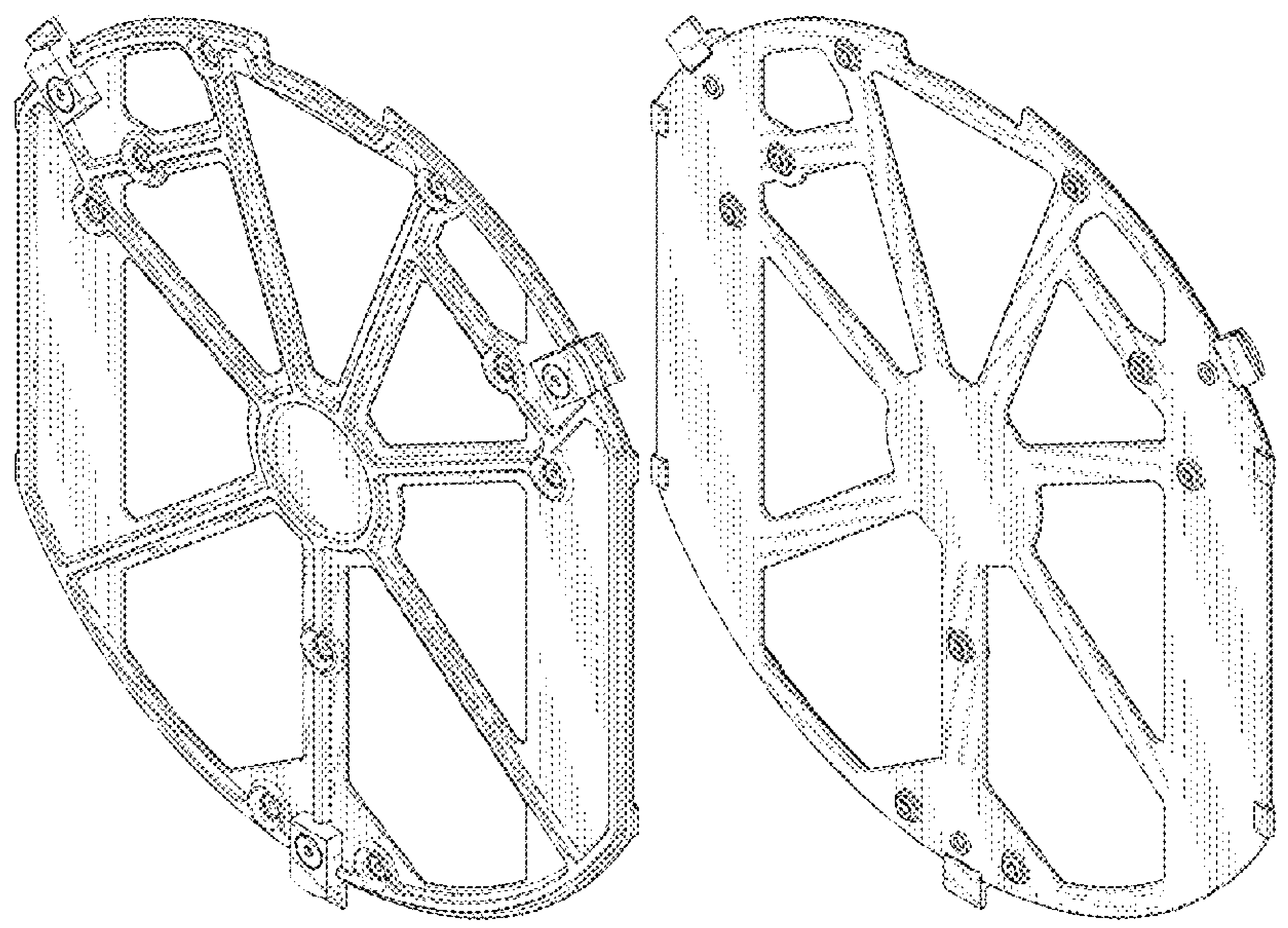
The ornamental design for a substrate processing system carrier, as substantially shown and described.

DESCRIPTION

FIG. **1** shows a top perspective view of a substrate processing system carrier in accordance with the present invention;
FIG. **2** shows a bottom perspective view thereof;
FIG. **3** shows a top plan view thereof;
FIG. **4** shows a bottom plan view thereof;
FIG. **5** shows a left side elevation view thereof;
FIG. **6** shows a right side elevation view thereof;
FIG. **7** shows a front elevation view thereof;
FIG. **8** shows a rear elevation view thereof;
FIG. **9** shows a top perspective view thereof in its intended environment; and,
FIG. **10** shows a top perspective view thereof in its intended environment.

The broken lines in the drawings illustrate environment that forms no part of the claimed design.

1 Claim, 8 Drawing Sheets



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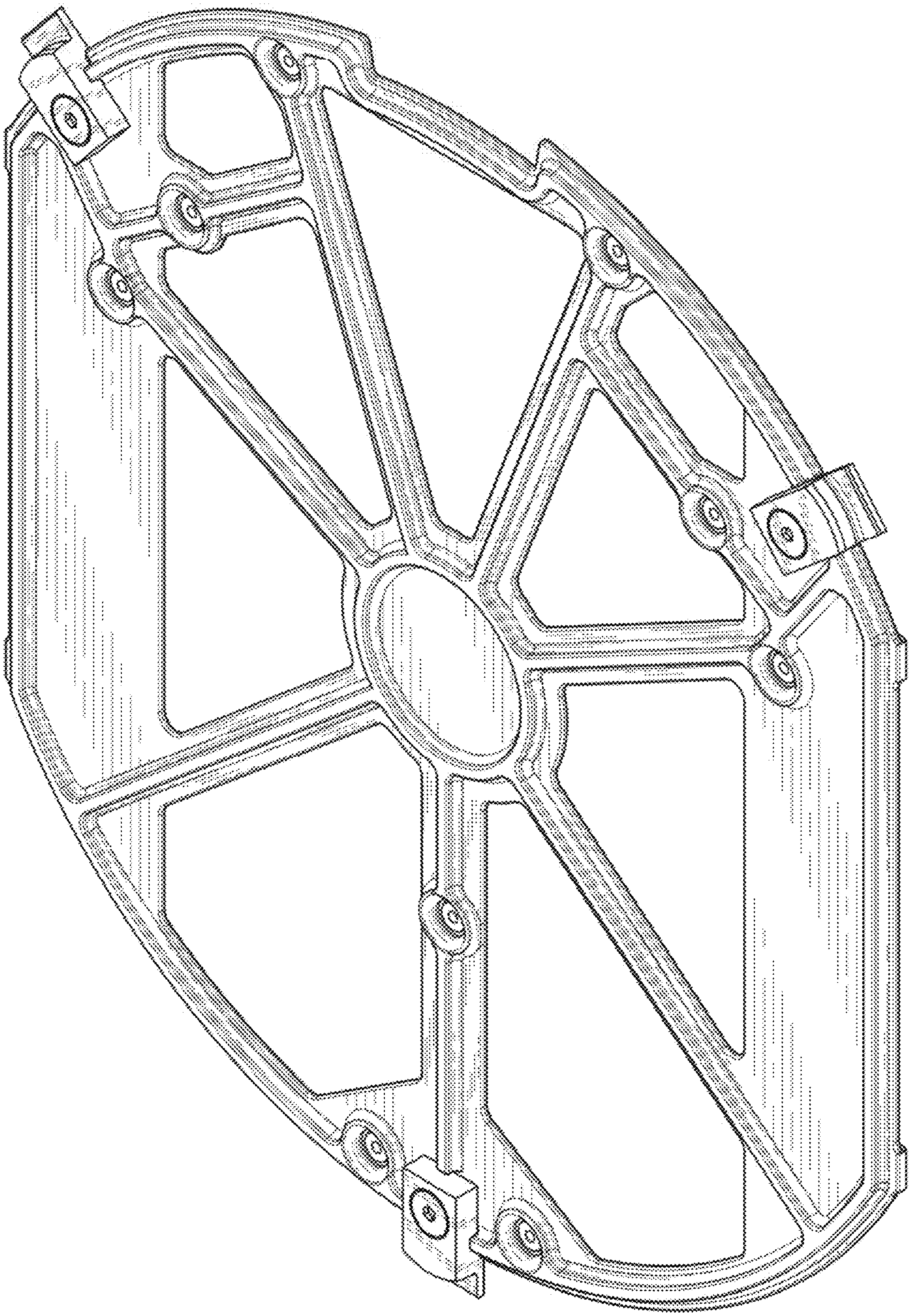


FIG. 1

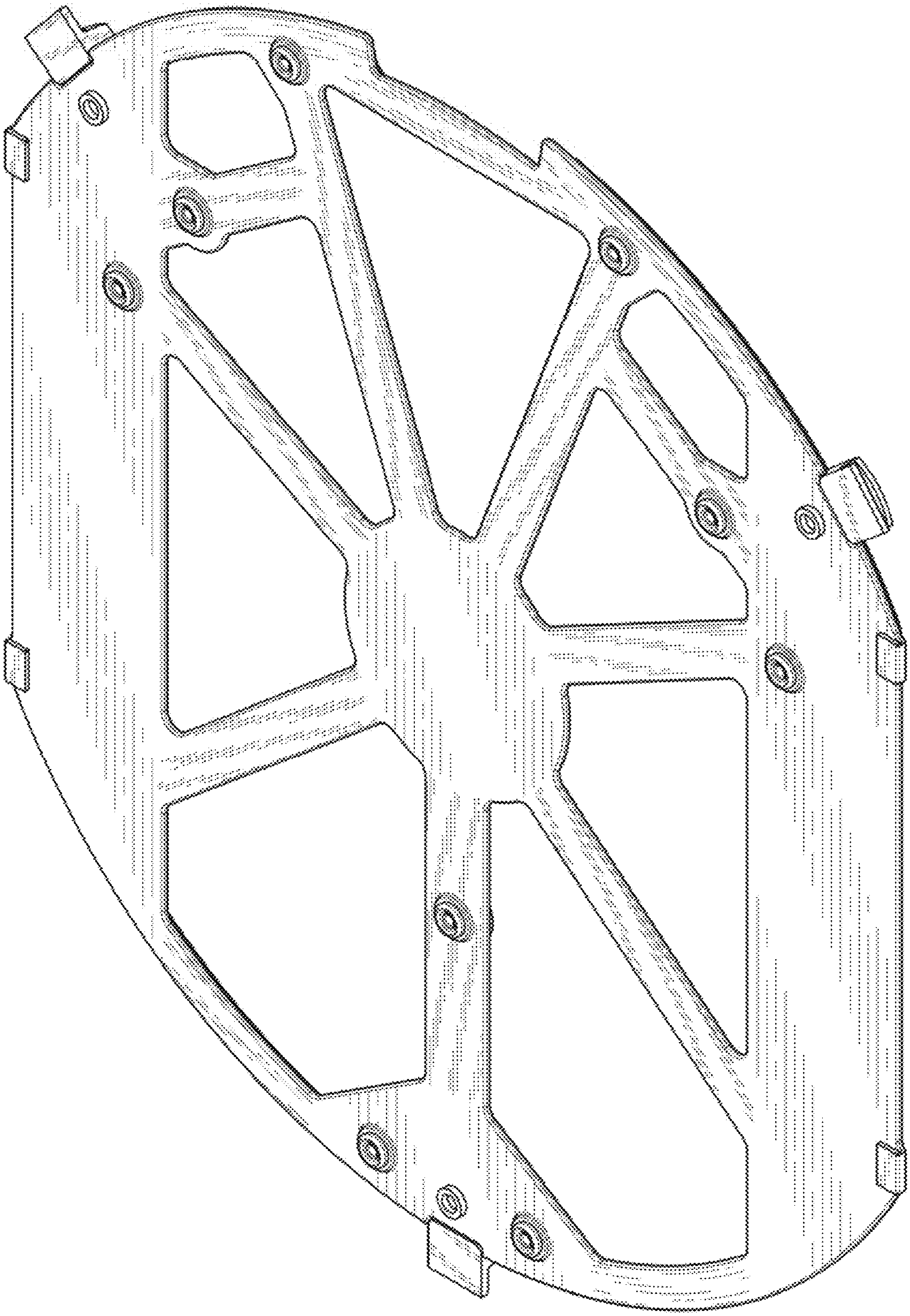


FIG. 2

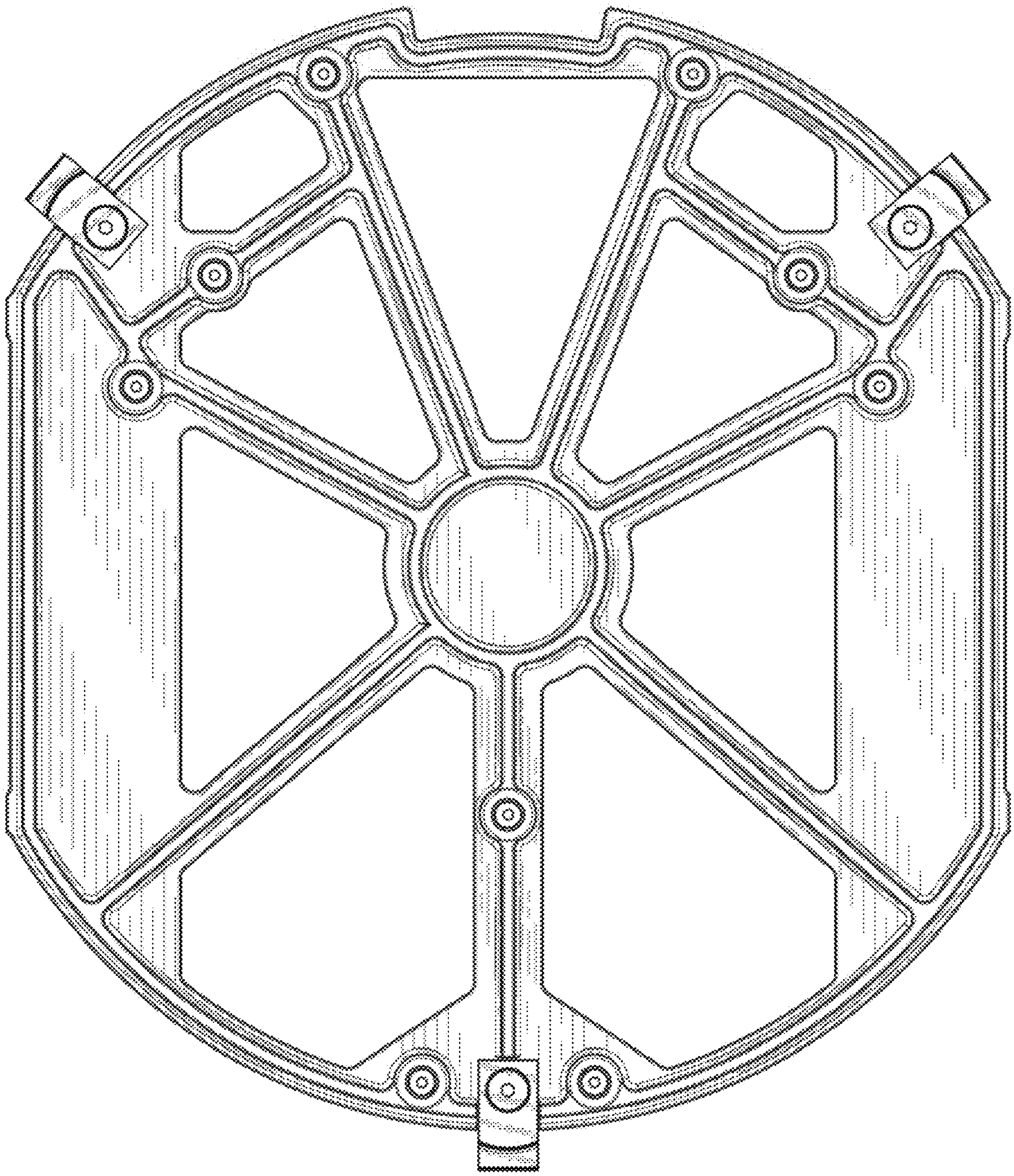
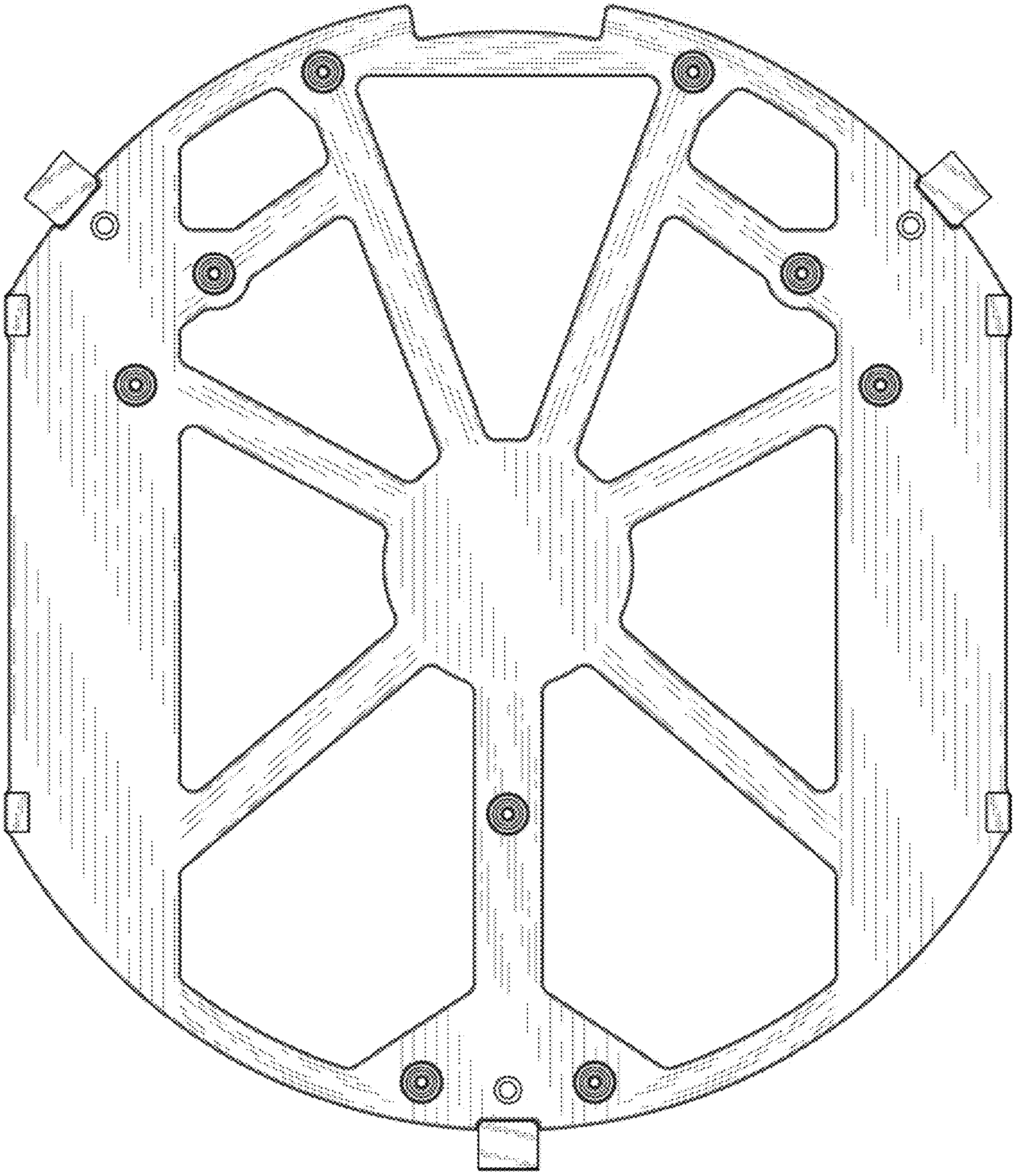


FIG. 3



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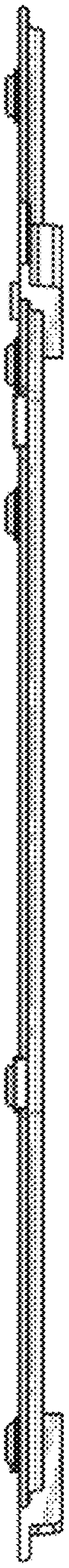

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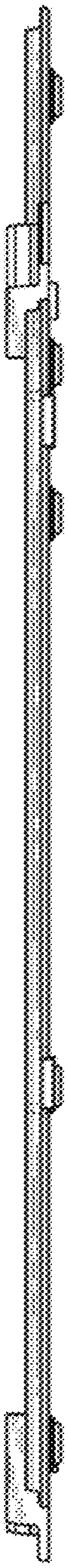
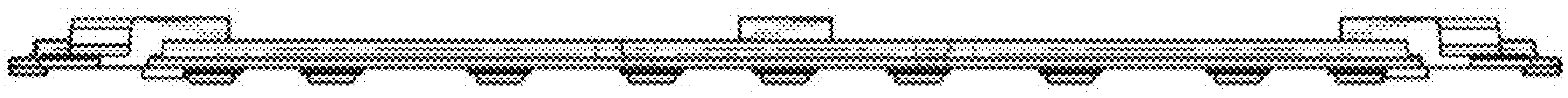


FIG. 6



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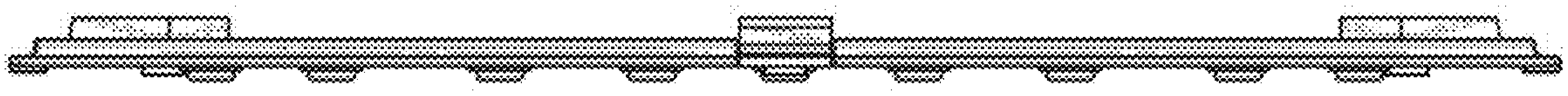

FIG. 8

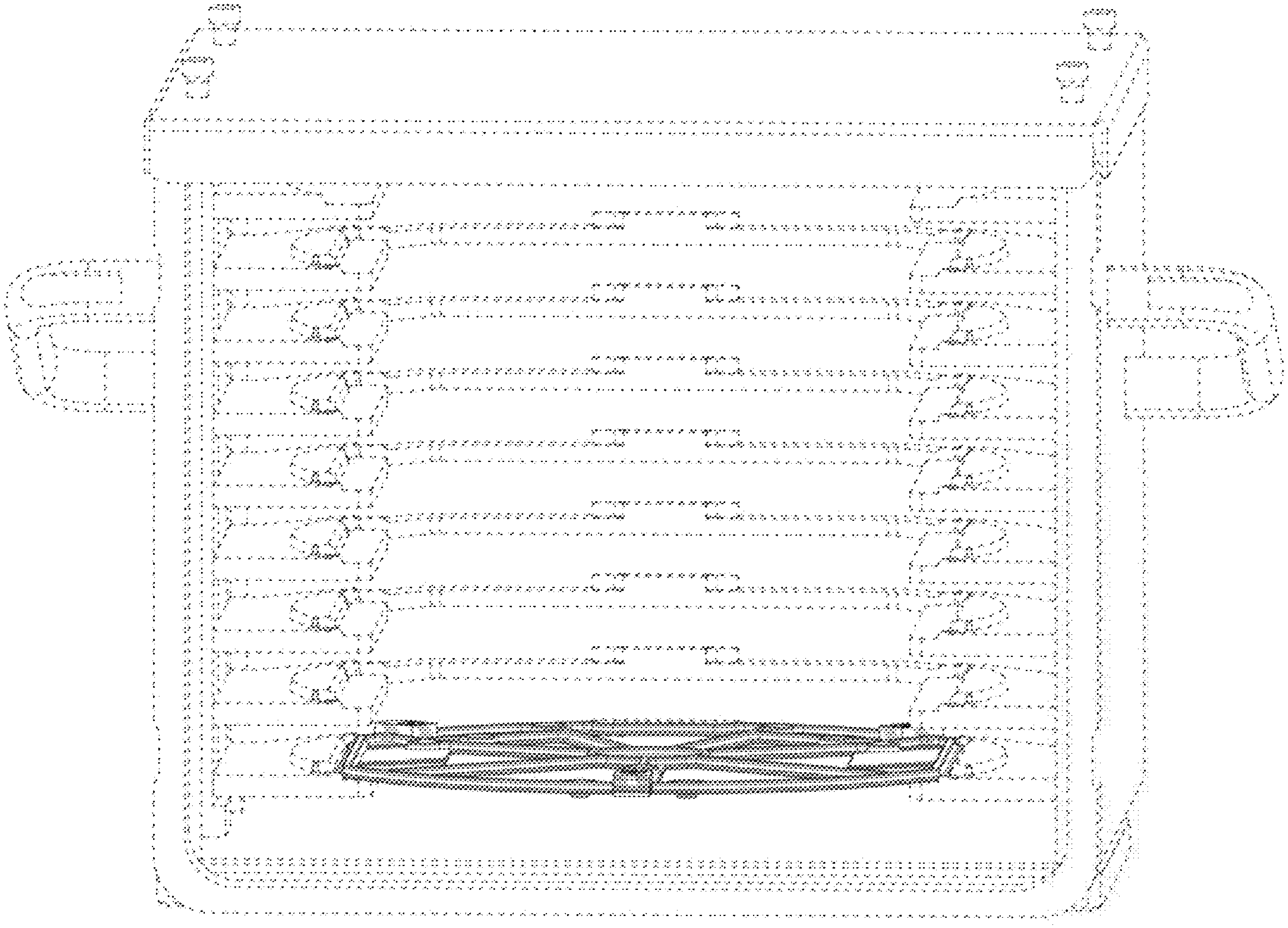

FIG. 9

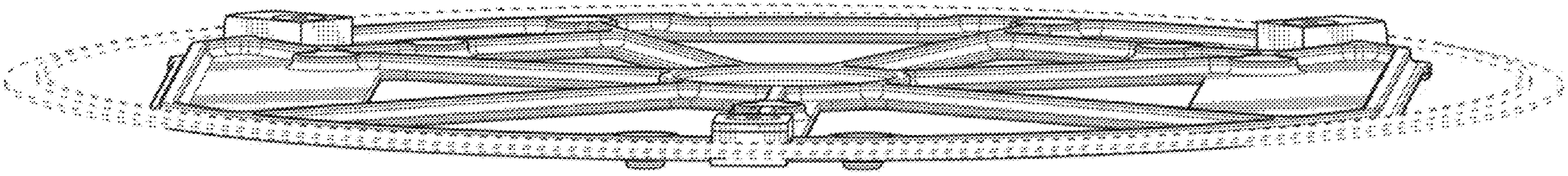

FIG. 10